

Part Number

SECG1WA0EY-S

● Package: 3.0 × 1.4 × 1.2t Surface Mount LED

• Color: White

Application : Automotive, Consumer Electronics,

Office Automation, Indicator

● Features : MSL-3, RoHS compliant,

Compatible with heat-resistance of lead-free solder.

Parameter	Symbol	Ratings		Unit		Remark	
Power dissipation	PD	108		mW			
Forward current	IF	30		mA			2
Forward current reduction ratio	ΔIF	-0.76		mA∕°C		Avobe 60°	C
Pulse forward current	IFP	70		mA		equency: f= e width: tw≦	
Reverse voltage	VR	3		v			
Operating temperature	Topr	-40~85		°C	·		
Storage temperature	Tstg	-40~100	C (°C			
Junction temperature	Tjmax	100		°C			
Electrical / Optical ch		2º					Ta=25

Electrical / Optical characteristics

Electrical / Optical	characte	ristics	7			Ta=25°C
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF=20mA		3.1	3.6	V
Reverse current	IR	VR=3V			10	μA
Luminous intensity $\%1$	IV	IF=20mA	747	1037	1327	mcd
Chromaticity X		IF=20mA		0.307		-
coordinates %2	У	IF-2011A		0.315		-
Directivity	2 <i>θ</i> 1/2	IF=20mA		120		degree
Thermal resistance	θj−a	_		300		°C/W

$\times 1$ Luminous intensity rank (Tolerance: $\pm 20\%$)

Rank	Luminous intensity range (mcd)			
E	747	~	996	
F	996	~	1327	

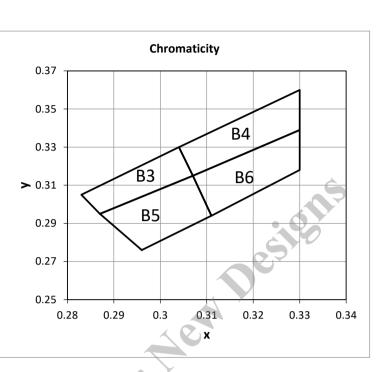




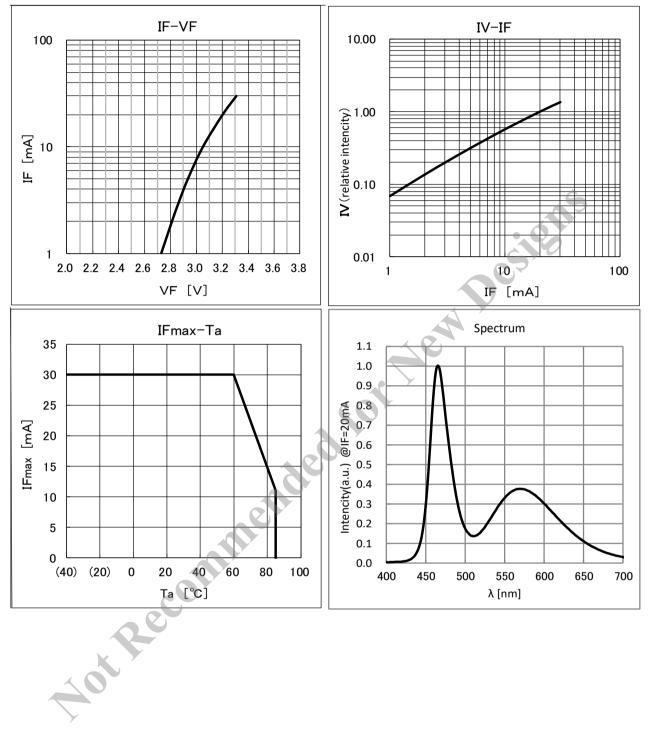


※2 Chromaticity Rank

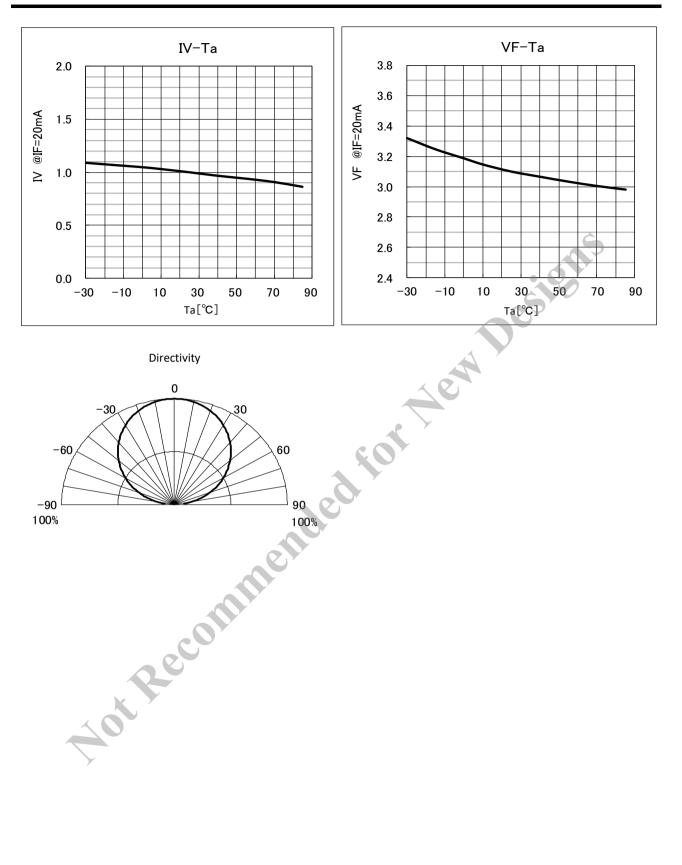
Chroma		У	х	Rank
	0.37 -	0.295	0.287	
	0.57	0.315	0.307	B3
	0.35 -	0.33	0.304	5
		0.305	0.283	
	0.33 -	0.315	0.307	
		0.339	0.33	В4
B3	> 0.31 -	0.36	0.33	D4
		0.33	0.304	
B5	0.29 -	0.276	0.296	
		0.294	0.311	DE
	0.27 -	0.315	0.307	B5
		0.295	0.287	
	0.25 -	0.294	0.311	
.28 0.29 0.3	0.	0.318	0.33	DC
		0.339	0.33	B6
		0.315	0.307	
γ	mend	com		
		~	oth	







• Characteristic data

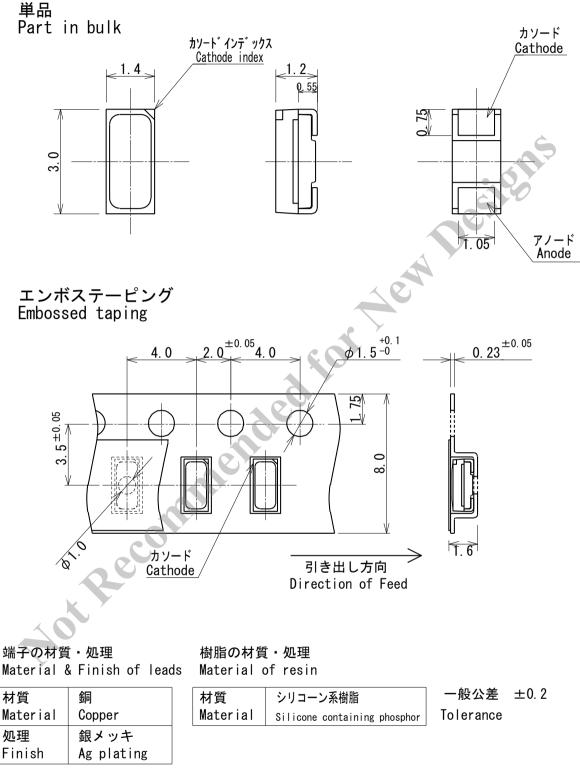


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• Outline

SEC*100E Series Outline dimensions



単位Unit:mm

Soldering conditions

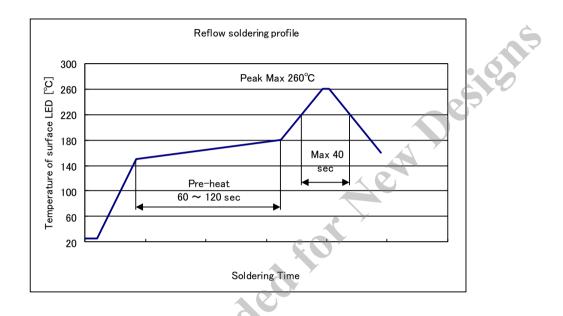
Following soldering conditions are recommended.

1 Reflow conditions (at the surface of LED resin)

Pre-heat :150 ~ 180 °C, 60 ~ 120 sec

Soldering temperature : 40sec Max above 220 °C. Peak temperature is 260 °C Max. Soldering must not be permitted more than 2 times.

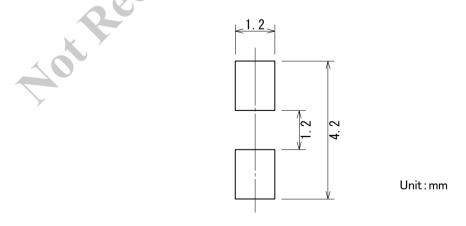
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2 Hand soldering

Temperature of soldering iron tip : 350±10°C, 5 sec Max. 1 time.

③ Recommended solder pad





Attention after opened

The LED is in SMD package. When the LED is mounted by means of soldering and the resin is unusually damp, soldering may cause interfacial defoliation. This occurs when a drastic temperature change causes moisture in the resin to evaporate and to swell. Therefore, attention to the below must be paid.

1 Atmosphere when using the LEDs after package is opened

After opened and mounted, soldering should be carried out quickly.

Following atmosphere is recommended when using (and mounting) the LEDs.

Temperature : 5~30°C Humidity : less than 70%

② Baking

In case 168 hours have passed after package is opened, LEDs must be dried as follows. Perform baking only once

 60 ± 5 °C for more than 24 hours (taping reel)

3 Storage after package is opened

Unused remaining LEDs should be stored with silica gel desiccants in a hermetically sealed container, Preferably the origin moisture-proof bags for storage Zipper. Following storage conditions are recommendedafter package is opened.

Temperature : 5~40°C Humidity : less than 30%

In case indicator color (blue) of desiccant (ex. silica gel) has disappeared, LEDs must be dried under the same conditions as 2 above.

Other

- After soldering any mechanical force or excessive vibration should not be applied to LEDs during cooling process until the LEDs cool down to normal temperature.
- 2 Quick cooling must be avoided.
- ③ The LEDs should not be mounted on warped direction of PCB.
- ④ Extra attention should be paid to the sealing resin of the product, which is silicone resin. When you handle a product with the sharp things, such as tweezers and a nail, please avoid it in resin. Removed product should not be used.
- ⑤ Please avoid contact to mounted LED.
- (6) This productseries emits high light power. Do NOT look directly into the light emitting area. Direct exposure to the light over an extended time period may har m eyes.
- ⑦ The silver plating of the lead frame may discolor if the product comes into contact with material containing sulfides or if it is exposed to an atmosphere containing sulfide gas.
- (8) Dispersion of VF and IV widely, if using the LED lamps with low current. When you use with low current, please be careful about varies widely. The LED Lamp is recommended to use with sorting current.

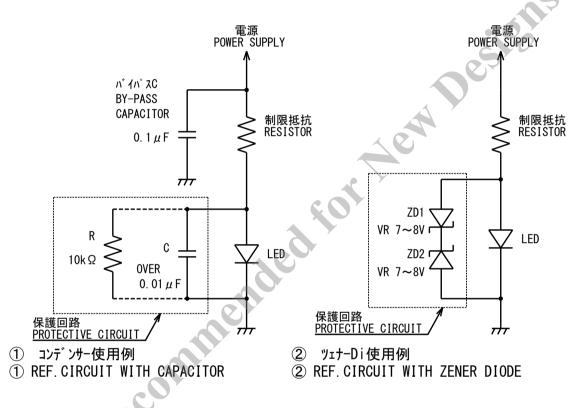


Electrostatic Discharge

Products are sensitive to static electricity and care shall be fully taken when handling Products. Particularly in case that an over-voltage which exceeds the Absolute Maximum Rating of Products shall be applied, the overflowed energy may cause damages to, or possibly result in destruction of Products. Buyer shall take absolutely secured countermeasures against static electricity and surge when handling products.

The circuit of unti-static and unti-surge

The anti-static and anti-surge reference circuit is shown below. Besides, the circuit is reference, Buyer shall sufficiently check static electricity and surge level when employing products.



The reference protection circuit with capacitor
The reference protection circuit with zener diode



Test Items	Times	Test Conditions
試験項目	試験期間	試験条件
Steady state Operating Life Test	1000h	Ta = Room Temperature
連続通電試験	Tuuun	IF = IFmax
Intermittent Operating Load Test	1000h	Ta = Room Temperature
断続通電試験	10001	IF = IFmax, on/off each 1min.
High Temperature Operating Life Test	1000h	JEITA ED-4701 101A
高温連続通電試験	10001	Ta = Topr max, IF = Ifmax at derating
High Temperature Storage Test	1000h	JEITA ED-4701 102A
高温保存試験	Tuuun	Ta = Tstg max
Low Temperature Storage Test	1000h	JEITA ED-4701 202A
低温保存試験	Tuuun	Ta = Tstg min
Moisture Resistance Test	1000h	JEITA ED-4701 103A
耐湿性試験	10001	Ta=60°C,RH=90%
Temperature Cycle Test	100c	JEITA ED-4701 105A
温度サイクル試験	1000	Ta = Tstg min ~ Tstg max each 30min.
		JEITA ED-4701 301D
Soldering Heat Test 1 はんだ耐熱性試験 1	2 times	Reflow Peak 260°C Max
		Infrared Reflow or Convection Reflow Soldering MSL3
Soldering Heat Test 2	1 times	350°C,3.5s
はんだ耐熱性試験 2	i times	Using soldering iron
Solder ability Test	1 4100	JEITA ED-4701/303A
はんだ付け性試験	1 times	245°C,5s, Using flux

Reliability Test Conditions

Failure Criter	ria
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はんだ利用性試験	245 C,5s, Using flux
● Failure Criteria	ende
Measurement Item	Failure Criteria
測定項目	故障判定基準
	MAX VFS × 1.2 (+20%) *
VF 順方向電圧	MIN VFS × 0.8 (-20%) *
	*初期値の±20%
IR	MAX UL×2 *
逆方向電流	* 規格の2倍
IV K	MIN IVS × 0.5 (-50%) *
光度	*初期値の50%

*はんだ付け性試験・・・95%以上はんだに覆われていること。

*Solderability ... The Lead shall be covered by solder at least 95%.

*VFS…Initial data of VF *UL…Upper limit of spec.

*IVS...Initial data of Luminous Intensity

*VFSはVF初期値、ULは規格上限値、IVSは光度の初期値。

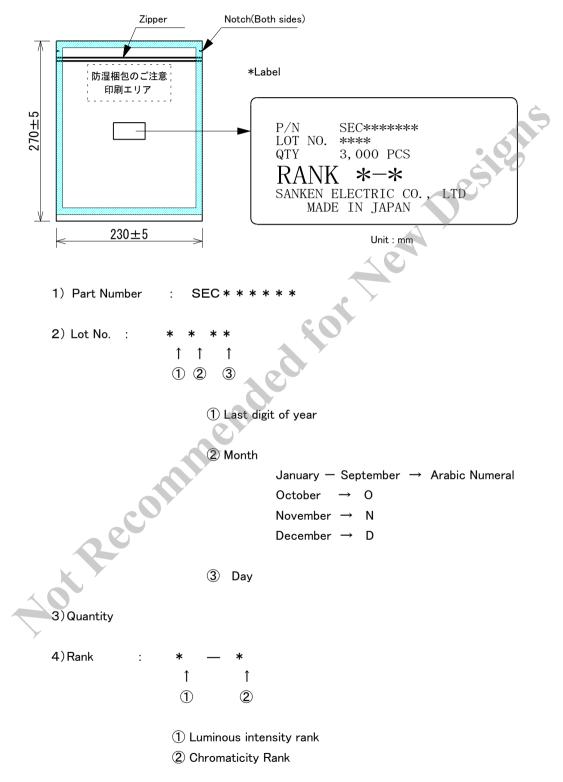


Packing

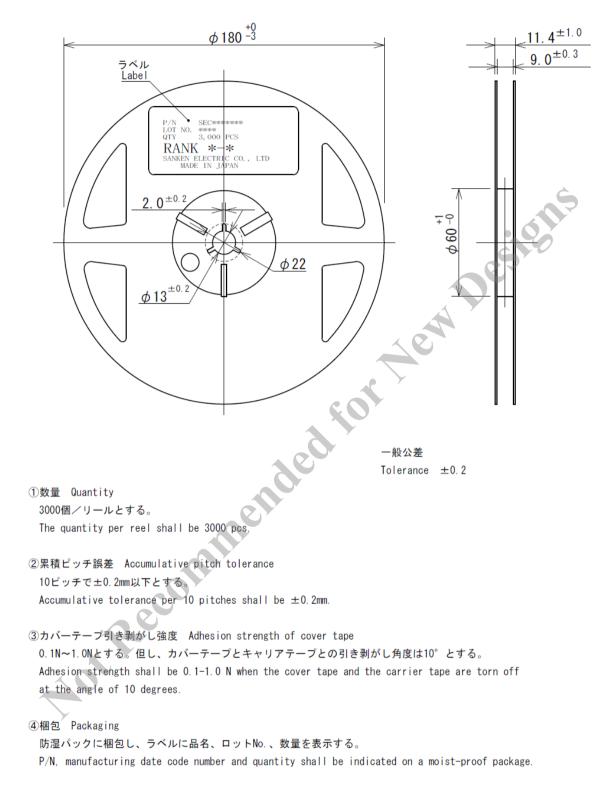
Minimum packing specifications

Packing Material : Aluminum laminated moisture-proof packing(desiccant, enclosure) Quantity : 3000 pcs (Minimum order quantity)

Label : See below



Taping reel dimensions



単位Unit:mm



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